IT-8300GA

IT-8300GA- Next Generation low DK Halogen free product for

- 4 G LTE Base Stations
- 5 G Base Stations & mm wave applications
- Antenna applications

Features

- Thermoset system with 205 ℃ Tg
- Very low loss ~0.0020 at 10 GHz.
- Halogen Free
- Excellent dimensional stability
- Very stable DK/Df with Temperature
- Ability to use very low profile Copper for reduced insertion loss.
- Highly suitable for Hybrids

Data sheet - IT-8300GA

Property			Units	IT-8300GA
			Units	DK-3.00
THERMAL	Thickness		mm	0.504(20 mils)
	Glass Transition Temp (Tg)	DMA	℃	210
		DSC		201
		TMA		200
	Time to Delam (T300)	With Cu	min.	> 60
	Solder Float		min.	> 60
	Solder Dip (PCT@1 hour and 121℃)			> 60
	Thermal Decompositiom Temp (5wt%)		℃	433
	CTE: RT-150℃	X-axis	ppm/℃	19.1
	CTE: RT-150℃	Y-axis	ppm/℃	20.0
	CTE:α1	Z - axis	ppm/℃	65
	CTE:α2	Z - axis	ppm/℃	280
	CTE	Z - axis	%	3.2
ELECTRICAL	Thickness			0.504(20 mils)
	Dielectric Constant (Dk)	@2GHz		3.01
		@3GHz		3.01
		@5GHz		3.01
		@10GHz		3.00
	Dielectric Factor (Df)	@2GHz		0.0018
		@3GHz		0.0018
		@5GHz		0.0019
		@10GHz		0.0020
PHYSICAL	Water Absorption		%	0.22
	Peel Strength	1 oz (RTF)	lb/in	>4.0
	Flammability	-	Second	V0
	Thermal Conductivity		W/(mx˚ C)	0.52
	Elastic modulus	X-axis	GPa	14.10
		Y-axis	GPa	14.60